Protection Devices

TVS (Transient Voltage Suppressor Diodes)

ESD108-B1-CSP0201

Bi-directional, 5.5 V, 0.28 pF, 0201, RoHS and Halogen Free compliant

ESD108-B1-CSP0201

Data Sheet

Revision 1.4, 2016-04-21
Final

Power Management & Multimarket

Edition 2016-04-21

Published by
Infineon Technologies AG
81726 Munich, Germany

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (**www.infineon.com**)

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

1 Product Overview

1.1 Features

- ESD / transient protection of high speed data lines according to:
  - **IEC61000-4-2 (ESD): ±25 kV (air/contact discharge)**
  - **IEC61000-4-4 (EFT): ±2.5 kV / ±50 A (5/50 ns)**
  - **IEC61000-4-5 (surge): ±2.5 A (8/20 µs)**
- Bi-directional working voltage up to: V_{RWM} **= ±5.5 V**
- Line capacitance: C_L **= 0.28 pF (typical) at** f **= 1 MHz**
- Clamping voltage: V_{CL} **= 20 V (typical) at** I_{TLP} **= 16 A** with R_{DYN} **= 0.78 Ω (typical)**
- Very low reverse current: I_R **< 1 nA (typical)**
- Minimized clamping overshoot due to extremely low parasitic inductance
- Small form factor SMD Size 0201 and low profile (0.58 mm x 0.28 mm x 0.15 mm)
- Bidirectional and symmetric I/V characteristics for optimized design and assembly
- Pb-free (RoHS compliant) and halogen free package

Guidelines for optimized PCB design and assembly process available [2]

RoHS

1.2 Application Examples

- USB 3.0, Firewire, DVI, HDMI, S-ATA, DisplayPort, Thunderbolt
- Mobile HDMI Link, MDDI, MIPI, SWP / NFC
- Dedicated solution to boost space saving and high performance in miniaturized modern electronics

1.3 Product Description

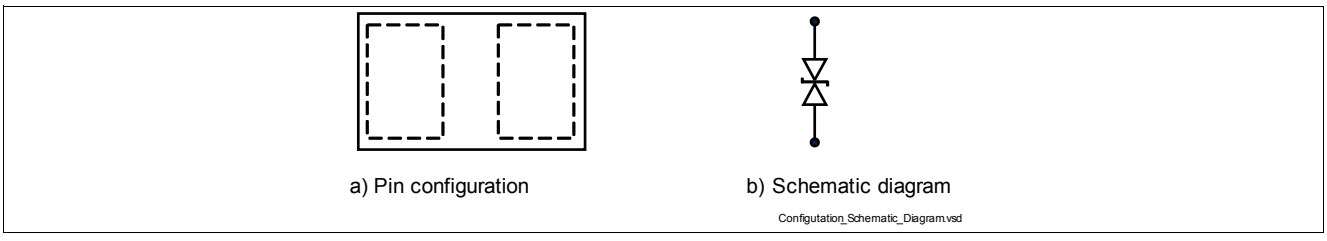

Figure 1-1 Pin Configuration and Schematic Diagram

Table 1-1 Part Information

Type	Package	Configuration	Marking code
ESD108-B1-CSP0201	WLL-2-1	1 line, bi-directional	C[1)]

1) The device does not have any marking or date code on the device backside. The Marking code is on pad side.

2 Maximum Ratings

Table 2-1 Maximum Ratings at T_A = 25 °C, unless otherwise specified [1)]

Parameter	Symbol	Values	Unit
Reverse working voltage	V_{RWM}	±5.5	
ESD (air / contact) discharge[2)]	V_{ESD}	±25	kV
Reverse working current	I_{RWM}	10	mA
Peak pulse power t_p = 8 / 20 µs[3)] t_p = 100 ns[2)]	P_{PK}	 27.5 18000	W
Peak pulse current[3)]	I_{PP}	±2.5	A
Operating temperature range	T_{OP}	-55 to 125	°C
Storage temperature	T_{stg}	-65 to 150	°C

1) Device is electrically symmetrical

2) V_{ESD} according to IEC61000-4-2 (R = 330 Ω, C = 150 pF discharge network)

3) Stress pulse: 8/20µs current waveform according to IEC61000-4-5

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the component.

Table 2-2 Thermal Resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Junction - soldering point[1)]	R_{thJS}	-	-	330	K/W

1) For calculation of R_{thJA} please refer to Application Note [3] 077 Thermal Resistance Calculation.

3 Electrical Characteristics at T_A = 25 °C, unless otherwise specified

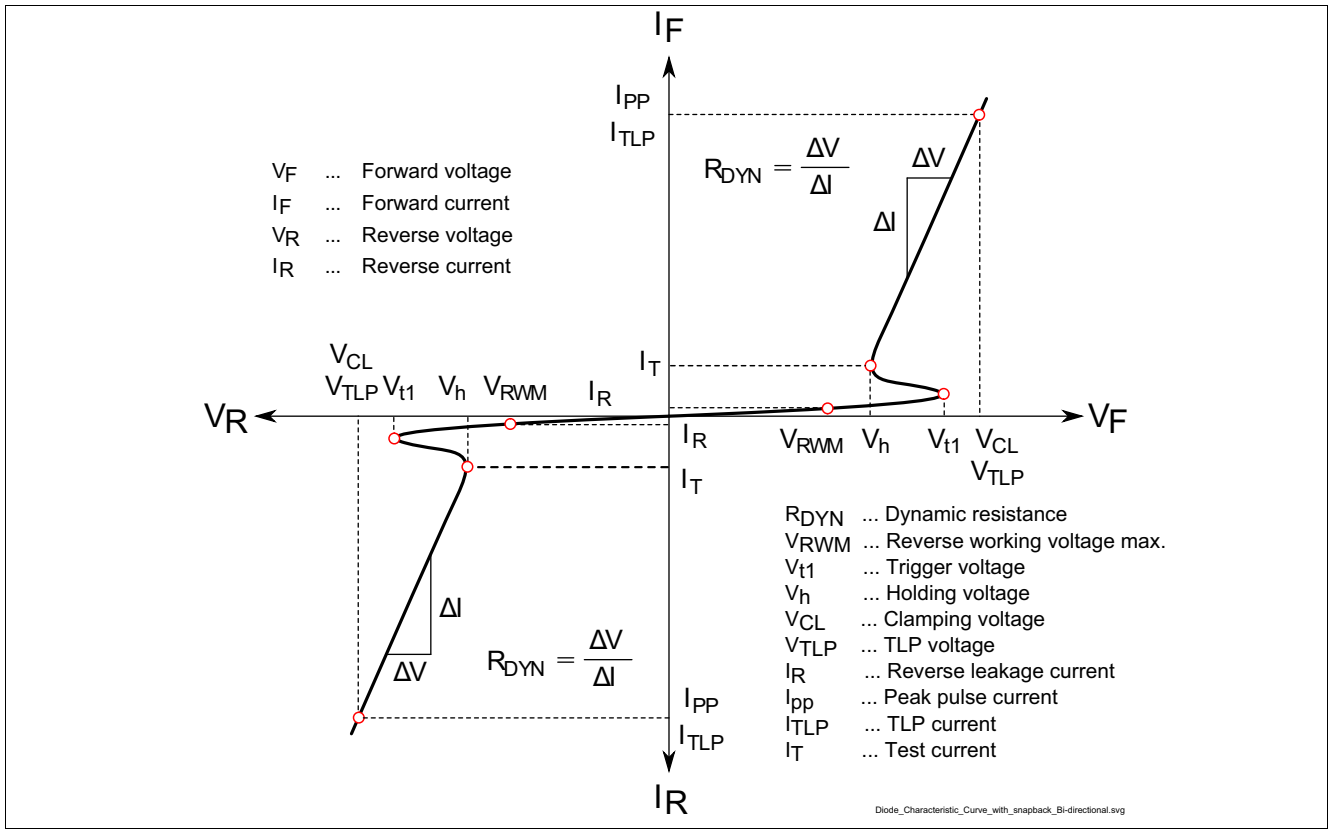

Figure 3-1 Definitions of electrical characteristics

Table 3-1 DC Characteristics at T_A = 25 °C, unless otherwise specified[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Reverse current	I_R	–	<1	20	nA	V_R = ±5.5 V
Trigger voltage	V_{t1}	–	9.5	12.5	V	
Holding voltage	V_h	5.5	6.5	9.5	V	I_T = 0.5 mA

1) Device is electrically symmetrical

Table 3-2 AC Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Line capacitance	C_L	–	0.28	0.38	pF	V_R = 0 V, f = 1 MHz
		–	0.22	0.38		V_R = 0 V, f = 1 GHz

Table 3-3 ESD and Surge Characteristics at T_A = 25 °C, unless otherwise specified [1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clamping voltage[2)]	V_{CL}	–	20	27	V	I_{TLP} = 16 A, t_p = 100 ns
		–	30.5	41		I_{TLP} = 30 A, t_p = 100 ns
Clamping voltage[3)]		–	20	–		V_{ESD} = 8 kV
		–	29	–		V_{ESD} = 15 kV
Clamping voltage[4)]		–	8.5	12		I_{PP} = 1 A, t_p = 8/20 µs
		–	11	18.5		I_{PP} = 2.5 A, t_p = 8/20 µs
Dynamic resistance[2)]	R_{DYN}	–	0.78	–	Ω	t_p = 100 ns

1) Device is electrically symmetrical

2) Please refer to Application Note AN210[1]. TLP parameter: Z_0 = 50 Ω , t_p = 100ns, t_r = 0.6 ns

3) V_{ESD} according to IEC61000-4-2 (contact discharge), V_{CL} at 30 ns (R = 330 Ω, C = 150 pF discharge network)

4) Stress pulse: 8/20µs current waveform according to IEC61000-4-5

4 Typical Characteristics Diagrams

Typical charateristics diagrams at T_A = 25 °C, unless otherwise specified

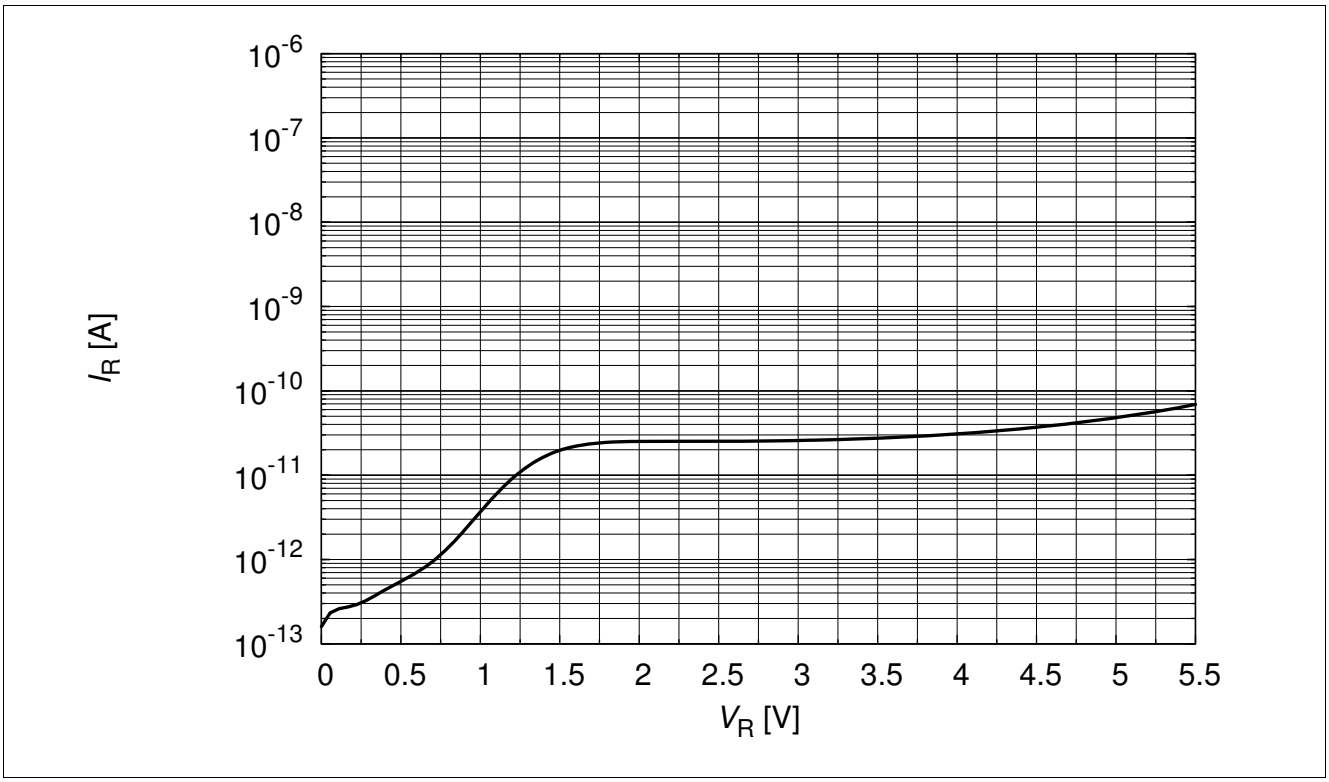

Figure 4-1 Reverse leakage current I_R = f(V_R)

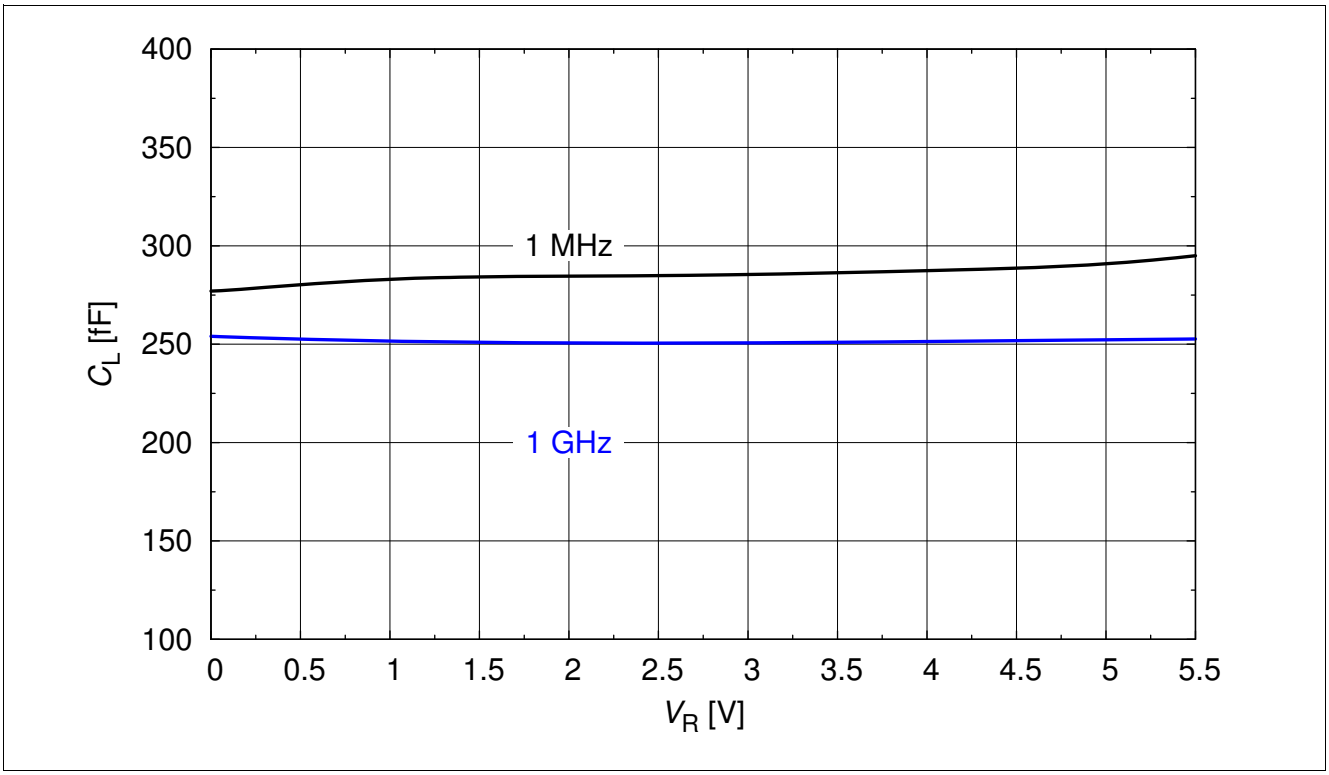

Figure 4-2 Line capacitance C_L = f(V_R)

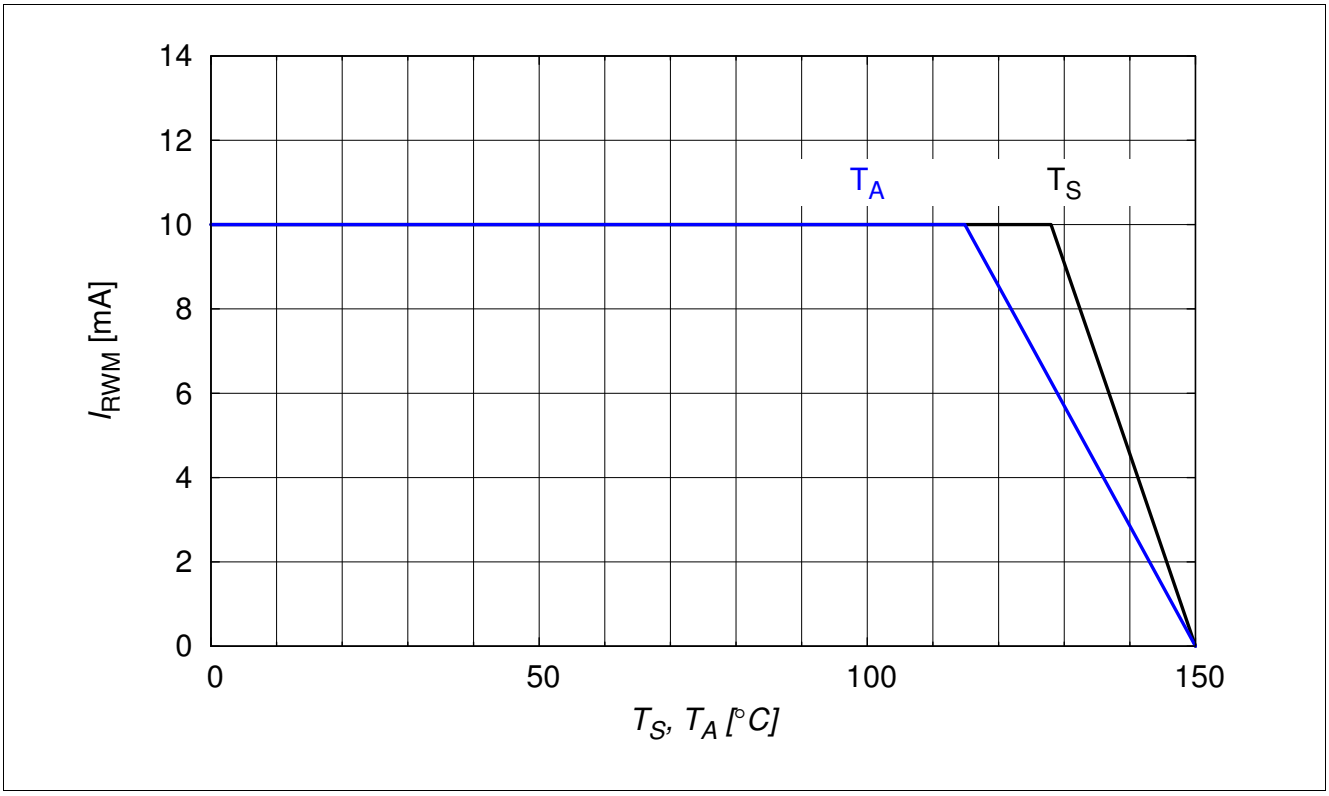

Figure 4-3 Reverse working current $I_{RWM} = f(T_S, T_A)$, Device mounted on PCB with R_{th} = 200 K/W [3]

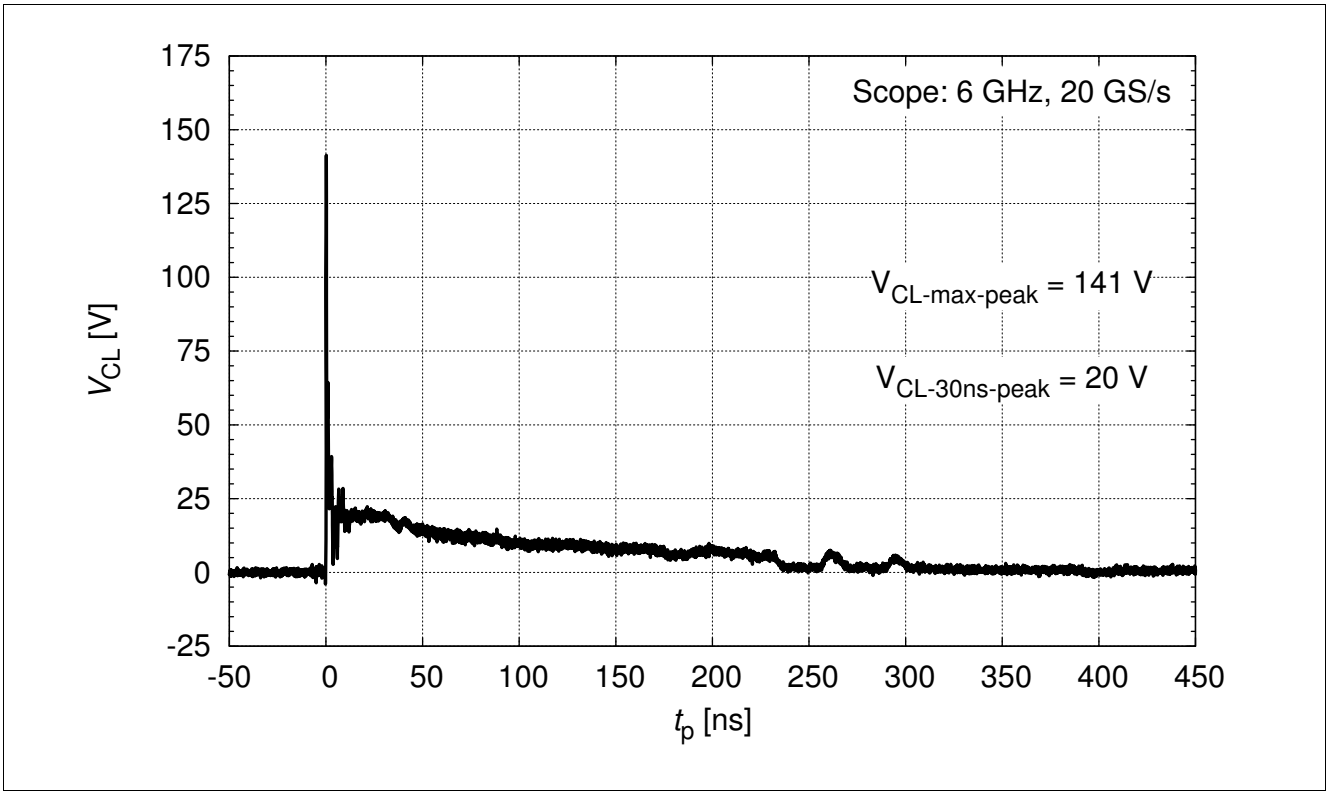

Figure 4-4 Clamping voltage (ESD): $V_{CL} = f(t)$, 8 kV positiv pulse

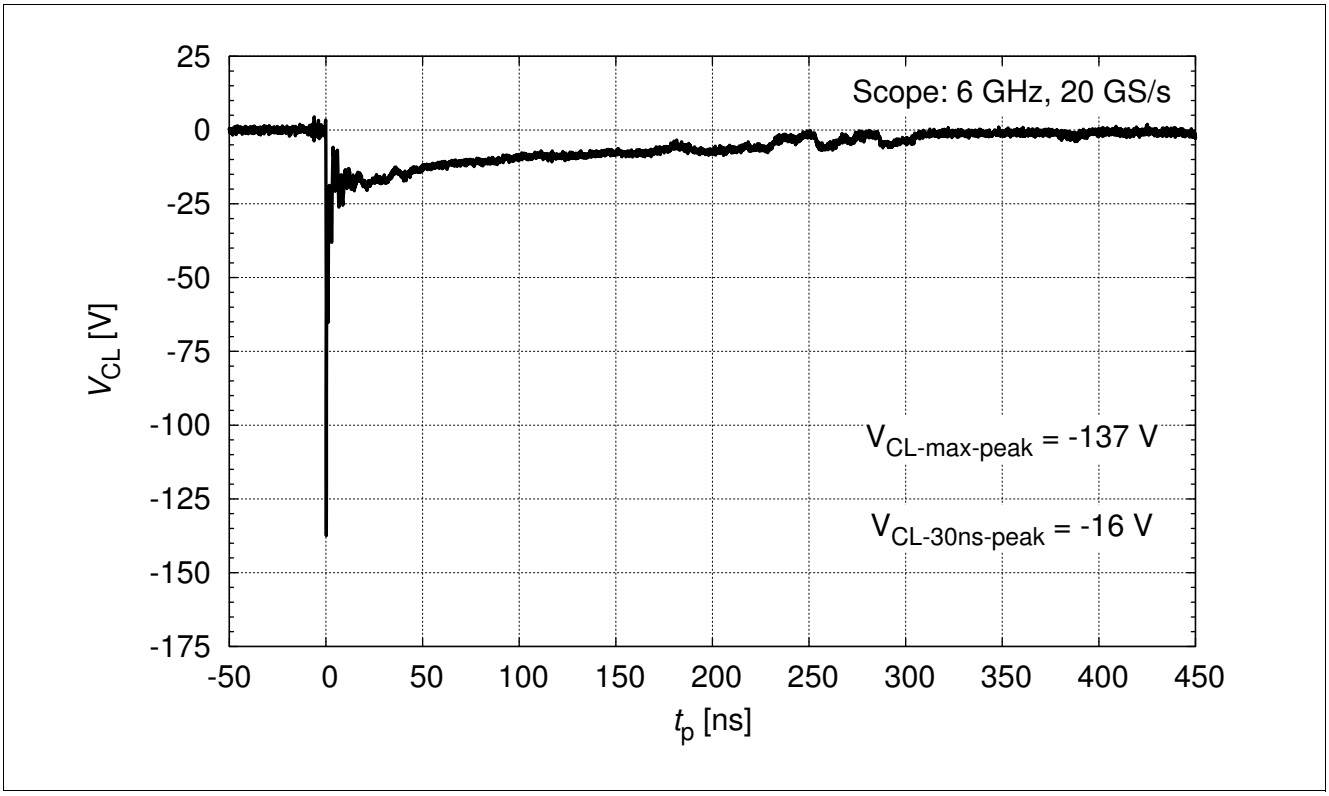

Figure 4-5 Clamping voltage (ESD): $V_{CL} = f(t)$, 8 kV negativ pulse

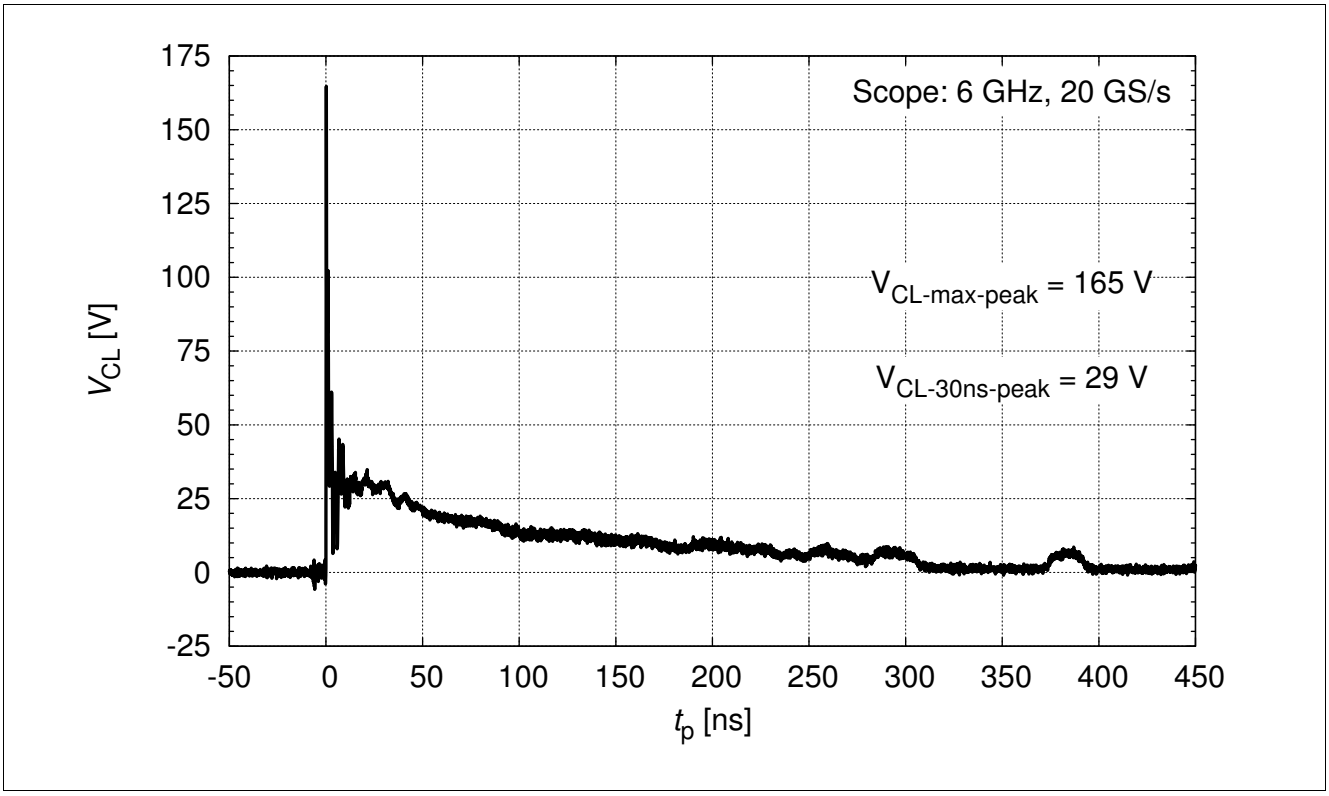

Figure 4-6 Clamping voltage (ESD): V_{CL} = *f*(*t*), 15 kV positiv pulse

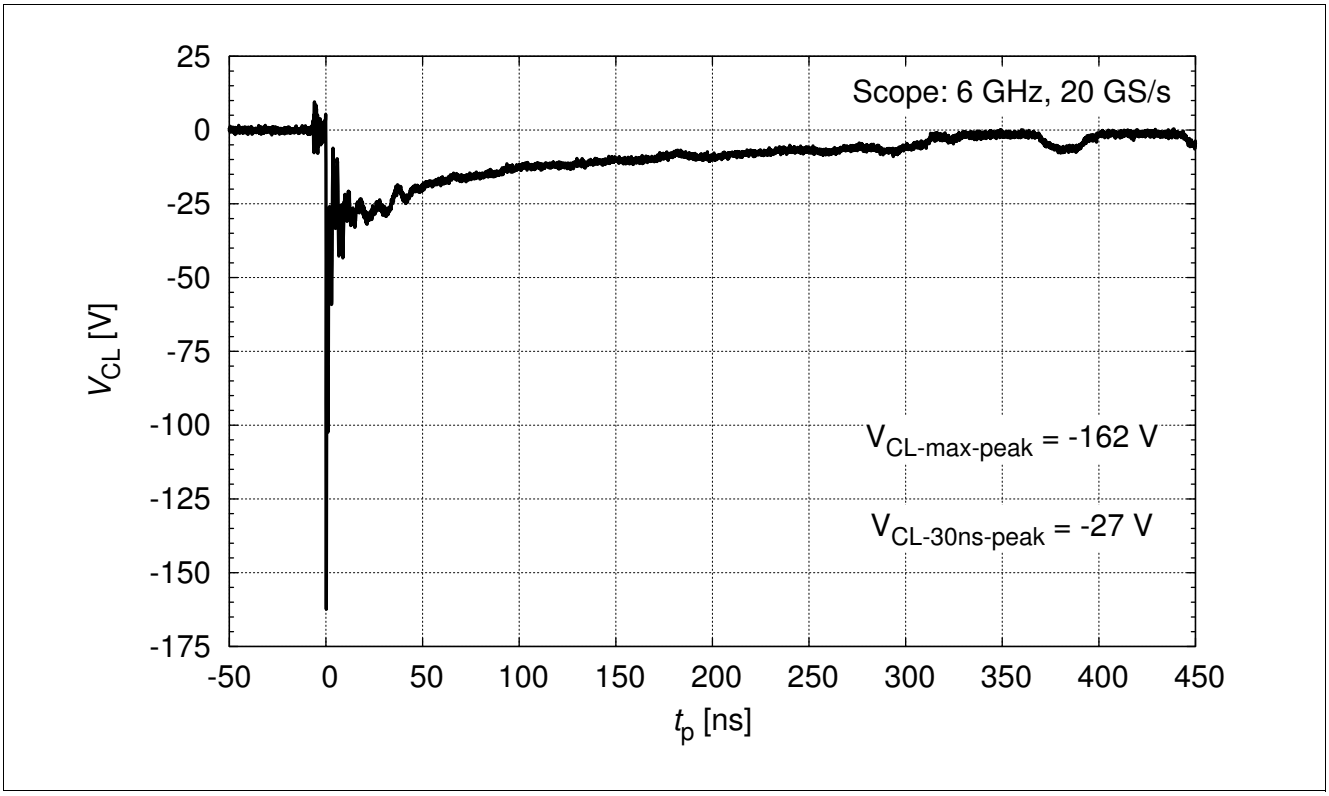

Figure 4-7 Clamping voltage (ESD): V_{CL} = *f*(*t*), 15 kV negativ pulse

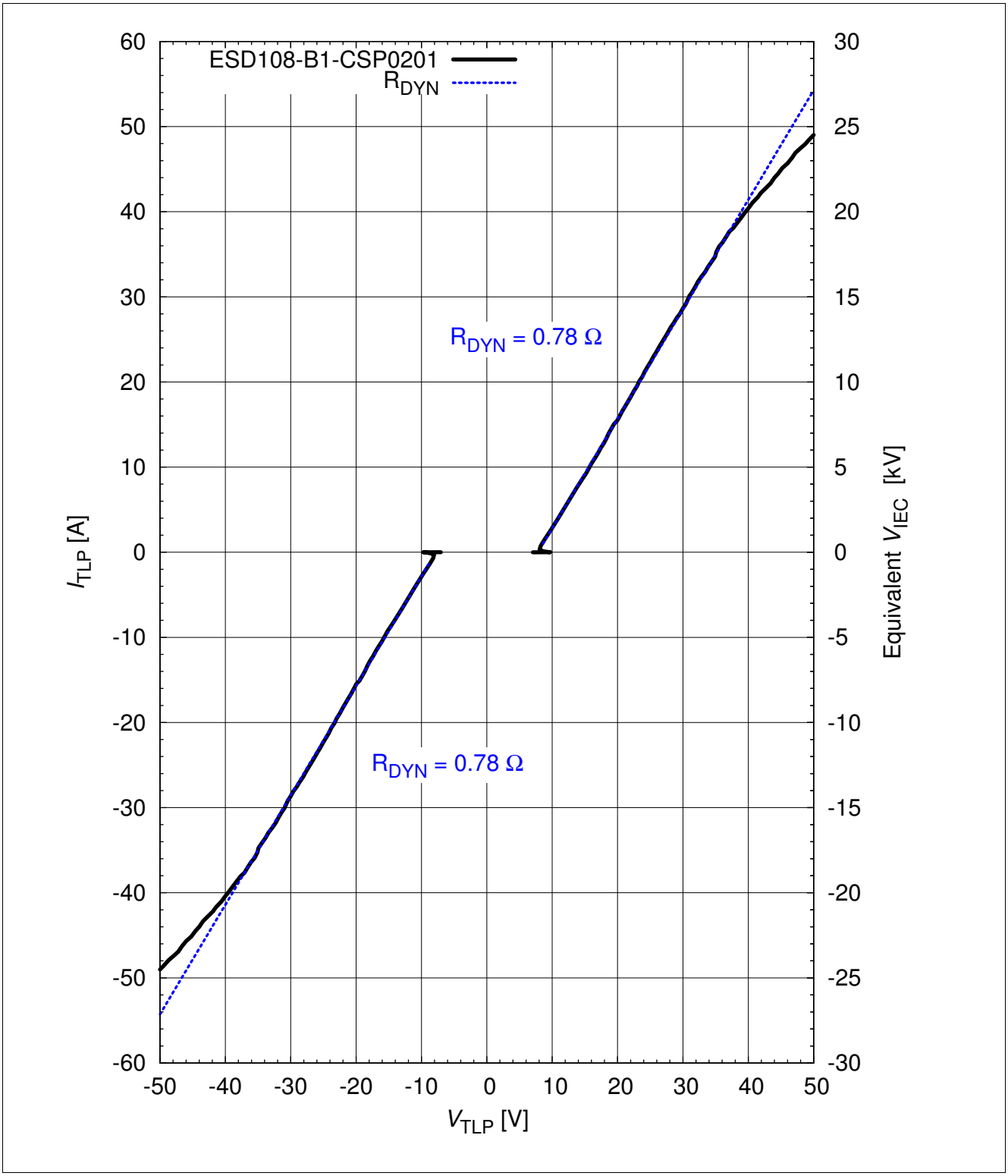

Figure 4-8 Clamping voltage (TLP): $I_{TLP} = f(V_{TLP})$ [1]

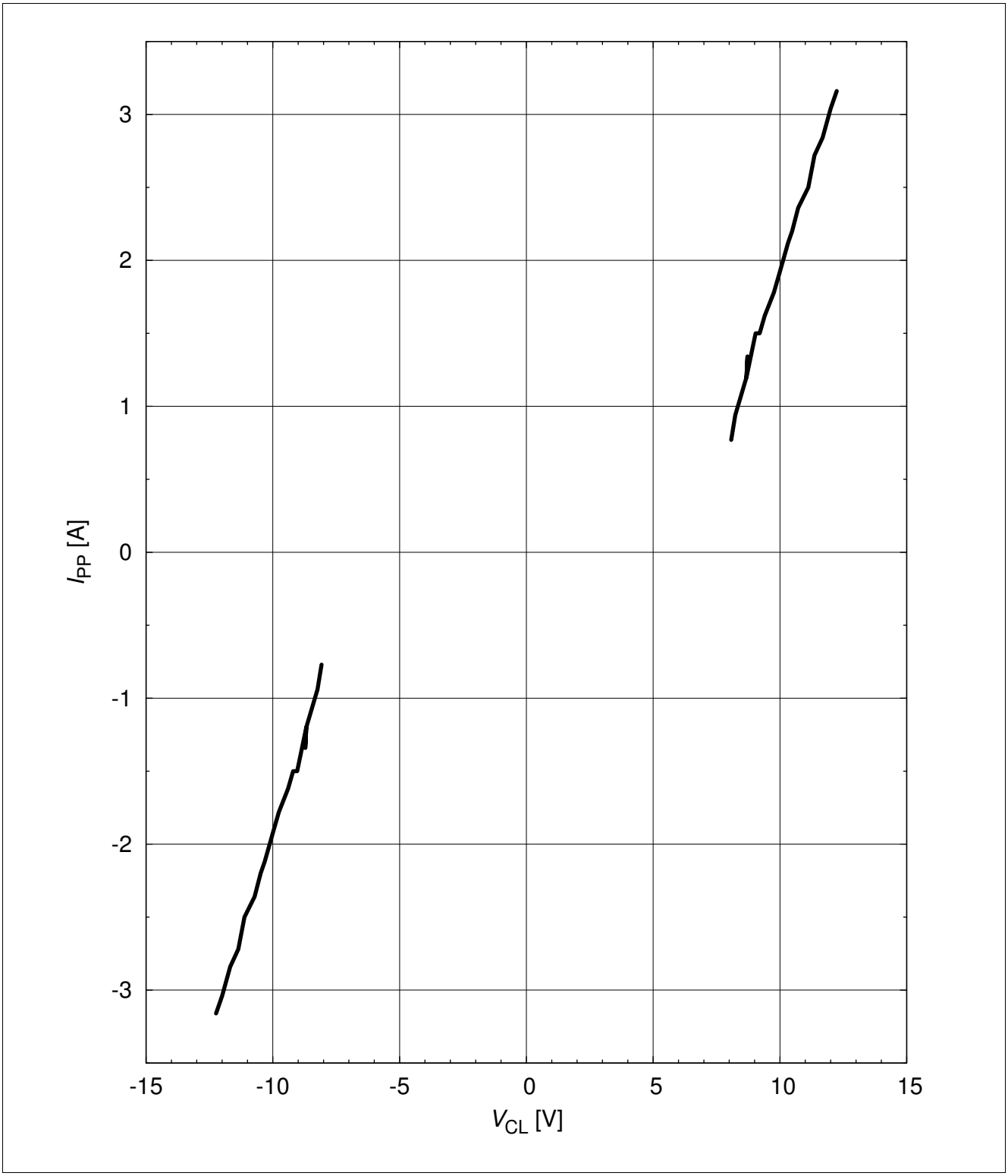

Figure 4-9 Clamping voltage (Surge): $I_{PP} = f(V_{CL})$ [1]

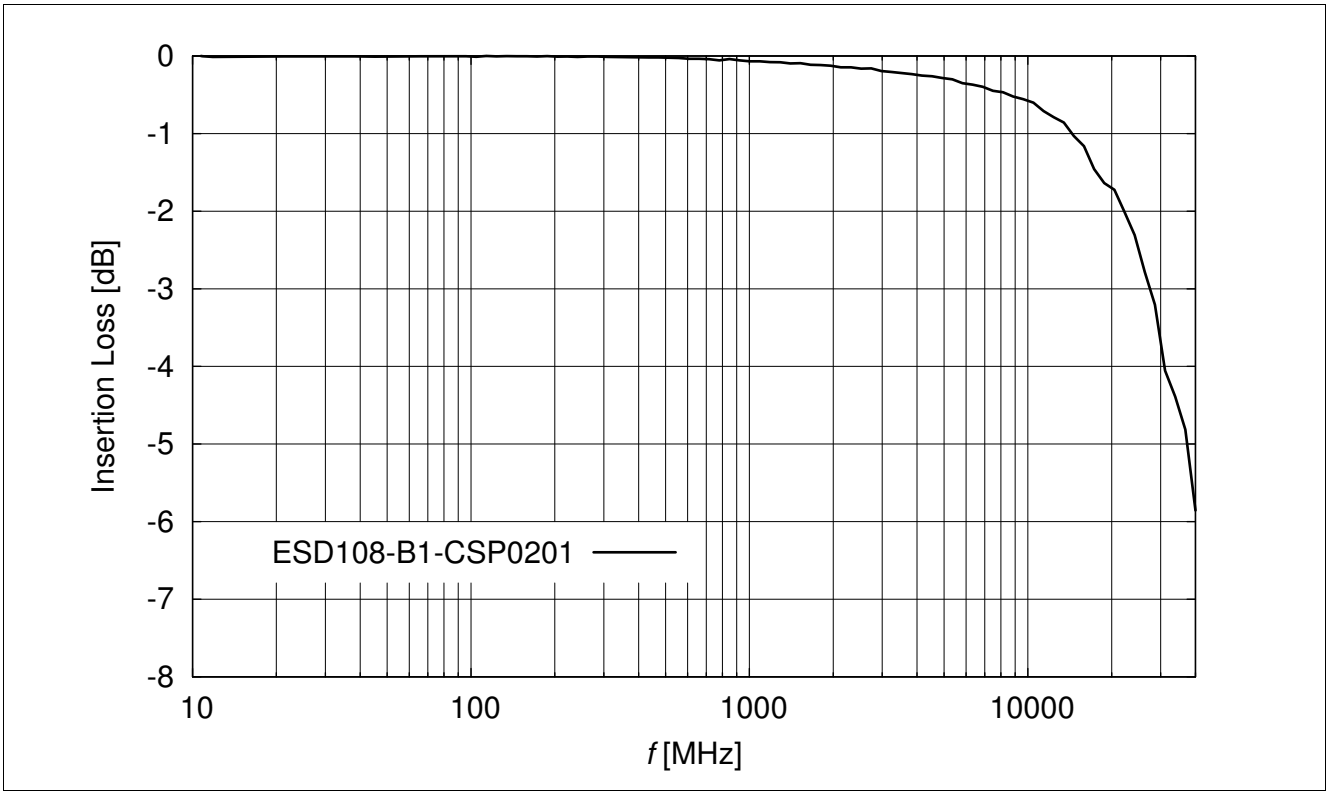

Figure 4-10 Insertion loss vs. frequency in a 50 Ω system

5 Package Information

5.1 WLL-2-1

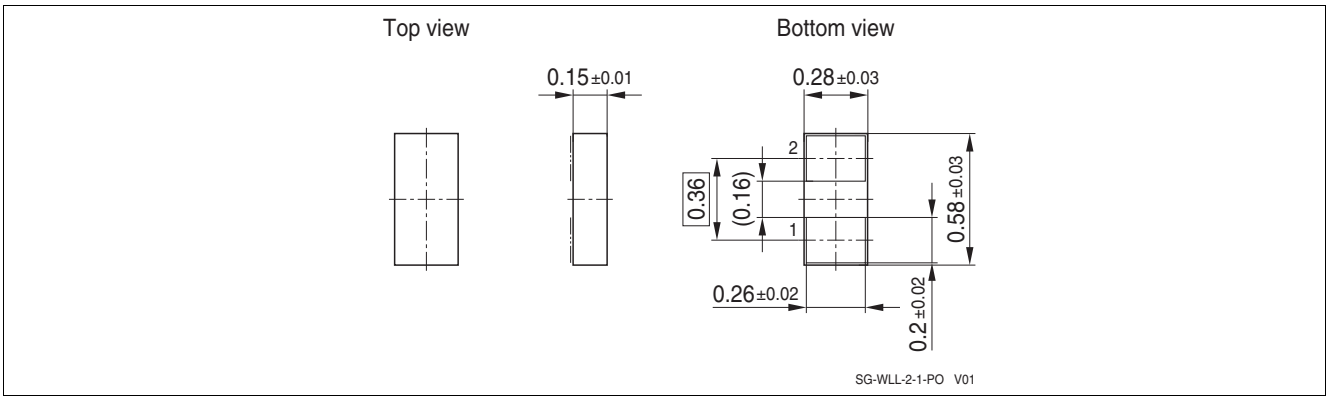

Figure 5-1 WLL-2-1 Package outline (dimension in mm)

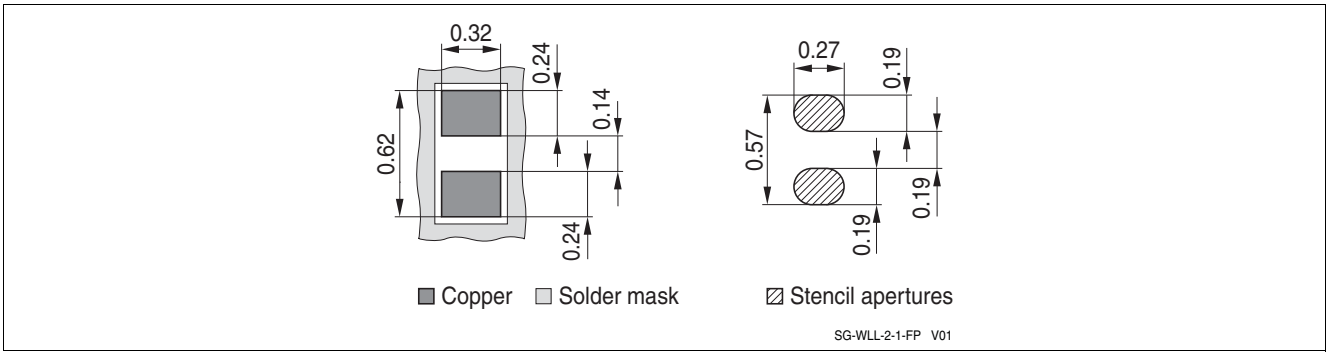

Figure 5-2 WLL-2-1 Footprint (dimension in mm) Recommendation for Printed Circuit Board Assembly[2]

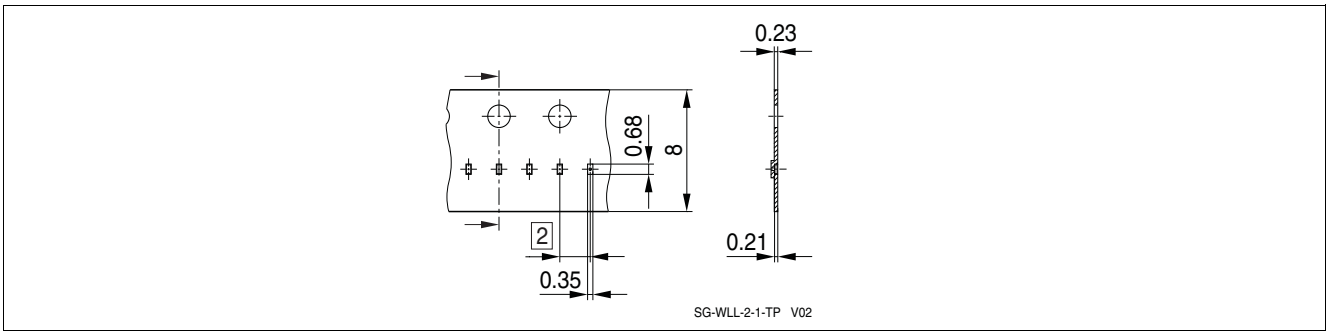

Figure 5-3 WLL-2-1 Packing (dimension in mm)

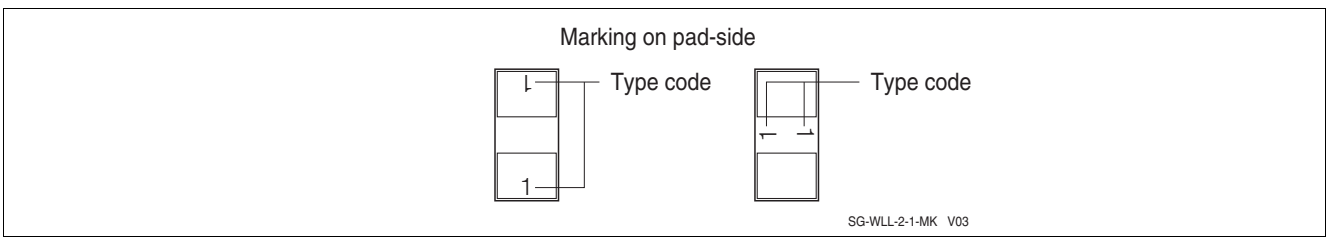

Figure 5-4 WLL-2-1 Marking example Table 1-1 “Part Information” on Page 3

References

[1] Infineon AG - **Application Note AN210:** Effective ESD Protection Design at System Level Using VF-TLP Characterization Methodology

[2] Infineon AG - Recommendation for Printed Circuit Board Assembly of Infineon WLL Packages

http://www.infineon.com/dgdl/?fileId=db3a304344f7b4f9014503db540027c0

[3] Infineon AG - **Application Note AN077:** Thermal Resistance Calculation

[4] Infineon AG - **Application Note AN392:** TVS Diodes in ChipScalePackage reduce size and save cost

Revision History: Rev. 1.3: 2015-01-19	
Page or Item	**Subjects (major changes since previous revision)**
Revision 1.4, 2016-04-21	
All	Layout update

Trademarks of Infineon Technologies AG

AURIX™, BlueMoon™, C166™, CanPAK™, CIPOS™, CIPURSE™, COMNEON™, EconoPACK™, CoolMOS™, CoolSET™, CORECONTROL™, CROSSAVE™, DAVE™, EasyPIM™, EconoBRIDGE™, EconoDUAL™, EconoPIM™, EiceDRIVER™, eupec™, FCOS™, HITFET™, HybridPACK™, I²RF™, ISOFACE™, IsoPACK™, MIPAQ™, ModSTACK™, my-d™, NovalithIC™, OmniTune™, OptiMOS™, ORIGA™, PRIMARION™, PrimePACK™, PrimeSTACK™, PRO-SIL™, PROFET™, RASIC™, ReverSave™, SatRIC™, SIEGET™, SINDRION™, SIPMOS™, SMARTi™, SmartLEWIS™, SOLID FLASH™, TEMPFET™, thinQ!™, TRENCHSTOP™, TriCore™, X-GOLD™, X-PMU™, XMM™, XPOSYS™.

Other Trademarks

Advance Design System™ (ADS) of Agilent Technologies, AMBA™, ARM™, MULTI-ICE™, KEIL™, PRIMECELL™, REALVIEW™, THUMB™, µVision™ of ARM Limited, UK. AUTOSAR™ is licensed by AUTOSAR development partnership. Bluetooth™ of Bluetooth SIG Inc. CAT-iq™ of DECT Forum. COLOSSUS™, FirstGPS™ of Trimble Navigation Ltd. EMV™ of EMVCo, LLC (Visa Holdings Inc.). EPCOS™ of Epcos AG. FLEXGO™ of Microsoft Corporation. FlexRay™ is licensed by FlexRay Consortium. HYPERTERMINAL™ of Hilgraeve Incorporated. IEC™ of Commission Electrotechnique Internationale. IrDA™ of Infrared Data Association Corporation. ISO™ of INTERNATIONAL ORGANIZATION FOR STANDARDIZATION. MATLAB™ of MathWorks, Inc. MAXIM™ of Maxim Integrated Products, Inc. MICROTEC™, NUCLEUS™ of Mentor Graphics Corporation. Mifare™ of NXP. MIPI™ of MIPI Alliance, Inc. MIPS™ of MIPS Technologies, Inc., USA. muRata™ of MURATA MANUFACTURING CO., MICROWAVE OFFICE™ (MWO) of Applied Wave Research Inc., OmniVision™ of OmniVision Technologies, Inc. Openwave™ Openwave Systems Inc. RED HAT™ Red Hat, Inc. RFMD™ RF Micro Devices, Inc. SIRIUS™ of Sirius Satellite Radio Inc. SOLARIS™ of Sun Microsystems, Inc. SPANSION™ of Spansion LLC Ltd. Symbian™ of Symbian Software Limited. TAIYO YUDEN™ of Taiyo Yuden Co. TEAKLITE™ of CEVA, Inc. TEKTRONIX™ of Tektronix Inc. TOKO™ of TOKO KABUSHIKI KAISHA TA. UNIX™ of X/Open Company Limited. VERILOG™, PALLADIUM™ of Cadence Design Systems, Inc. VLYNQ™ of Texas Instruments Incorporated. VXWORKS™, WIND RIVER™ of WIND RIVER SYSTEMS, INC. ZETEX™ of Diodes Zetex Limited.

Last Trademarks Update 2010-10-26

w w w . i n f i n e o n . c o m

Published by Infineon Technologies AG

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Infineon:
ESD108B1CSP0201XTSA1